

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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TSUBASA TSUKAHARA	11/08/2021
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PROPERTY NUMBERS Total: 1	
Property Type	Number
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NAME OF SUBMITTER:	MEGAN GODSEY FOR CHARLES J. KULAS
SIGNATURE:	/Megan A. Godsey/
DATE SIGNED:	11/11/2021

Total Attachments: 2

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Attorney Docket No. 020699-119000US
Sony ID No. SYP340059US01

PATENT

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **METHOD TO IMPROVE USER UNDERSTANDING OF XR SPACES BASED IN PART ON MESH ANALYSIS OF PHYSICAL SURFACES** for which application for Letters Patent of the United States of America has been filed on the date and has the serial number indicated below.

AND WHEREAS, **Sony Group Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075, Japan and Sony Corporation of America a New York corporation with offices at 25 Madison Avenue, New York, NY 10010** (hereinafter referenced as ASSIGNEE(S)) is desirous of securing all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in return for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto said ASSIGNEE(S), its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and any foreign countries, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America or any foreign country adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and foreign countries, including the right to sue for past infringement, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE(S), as the assignee(s) of the whole right, title and interest thereto;

I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE(S) or its designee, as ASSIGNEE(S) or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and foreign countries;

I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE(S) thereof shall hereafter require and prepare at its own expense;

I further agree that ASSIGNEE(S) will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with or impact in any way this assignment and sale;

I further agree that all obligations hereunder shall survive any termination of my employment and

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shall be binding on my heirs, executors, administrators, or other legal representatives or assigns;

I hereby authorize and request the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 17/488,254, Filing Date: September 28, 2021

This assignment is being executed on the date indicated below.

(1) Inventor: DocuSigned by:
Robert M. McCain
E104961894D1447... Date: 11/2/2021
Robert M. McCain

(2) Inventor: DocuSigned by:
Tsubasa Tsukahara
C6786300622242D... Date: 11/8/2021
Tsubasa Tsukahara